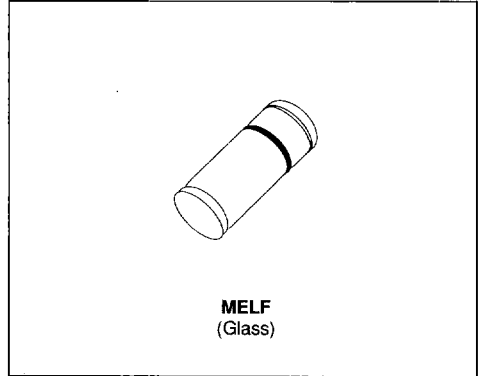


SMALL SIGNAL SCHOTTKY DIODE
DESCRIPTION

Metal to silicon rectifier diodes in glass case featuring very low forward voltage drop and fast recovery time, intended for low voltage switching mode power supply, polarity protection and high frequency circuits.


ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit
$I_{F(AV)}$	Average Forward Current	$T_I = 60^\circ\text{C}$ 1	A
I_{FSM}	Surge non Repetitive Forward Current	$T_I = 25^\circ\text{C}$ $t_p = 10\text{ms}$ 25 Sinusoidal Pulse	A
		$T_I = 25^\circ\text{C}$ $t_p = 300\mu\text{s}$ 50 Rectangular Pulse	
T_{stg}	Storage and Junction Temperature Range	- 65 to 150	$^\circ\text{C}$
T_j		- 65 to 125	$^\circ\text{C}$
T_L	Maximum Temperature for Soldering during 15s	260	$^\circ\text{C}$

Symbol	Parameter	BYV 10-20	BYV 10-30	BYV 10-40	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	20	30	40	V

THERMAL RESISTANCE

Symbol	Parameter	Value	Unit
$R_{th(j-l)}$	Junction-leads	110	$^\circ\text{C/W}$

* Pulse test : $t_p \leq 300\mu\text{s}$ $\delta < 2\%$.

ELECTRICAL CHARACTERISTICS

STATIC CHARACTERISTICS

Symbol	Test Conditions		Min.	Typ.	Max.	Unit
I_R^*	$T_j = 25^\circ\text{C}$	$V_R = V_{RRM}$			0.5	mA
	$T_j = 100^\circ\text{C}$				10	
V_F^*	$I_F = 1\text{A}$	$T_j = 25^\circ\text{C}$			0.55	V
	$I_F = 3\text{A}$				0.85	

** Pulse test : $t_p \leq 300\mu\text{s}$ $\delta < 2\%$.

DYNAMIC CHARACTERISTICS

Symbol	Test Conditions		Min.	Typ.	Max.	Unit
C	$T_j = 25^\circ\text{C}$	$V_R = 0$		220		pF

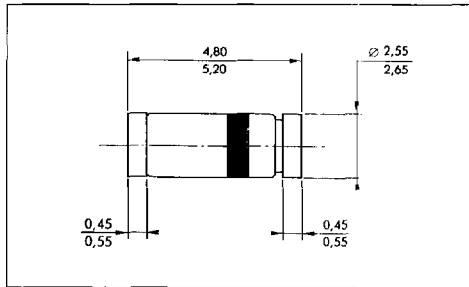
Forward current flow in a schottky rectifier is due to majority carrier conduction. So reverse recovery is not affected by stored charge as in conventional PN junction diodes.

Nevertheless, when the device switches from forward biased condition to reverse blocking state, current is required to charge the depletion capacitance of the diode.

This current depends only of diode capacitance and external circuit impedance. Satisfactory circuit behaviour analysis may be performed assuming that schottky rectifier consists of an ideal diode in parallel with a variable capacitance equal to the junction capacitance (see fig. 5 page 4/4).

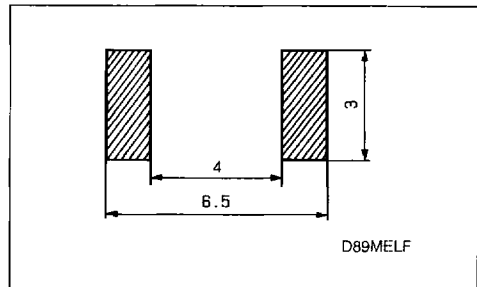
PACKAGE MECHANICAL DATA

MELF (Glass)



Cooling method : by convection and conduction
 Marking : ring at cathode end.
 Weight : 0.15g

FOOT PRINT DIMENSIONS (Millimeter)



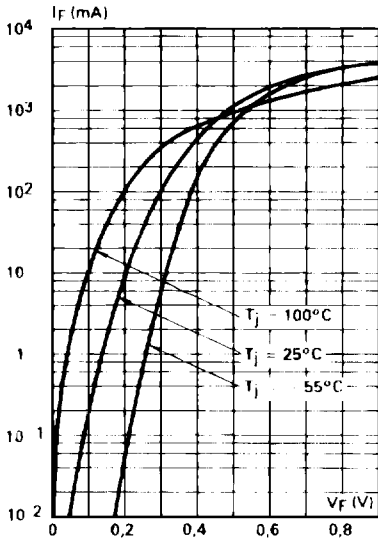


Fig.1 Forward current versus forward voltage at low level (typical values)

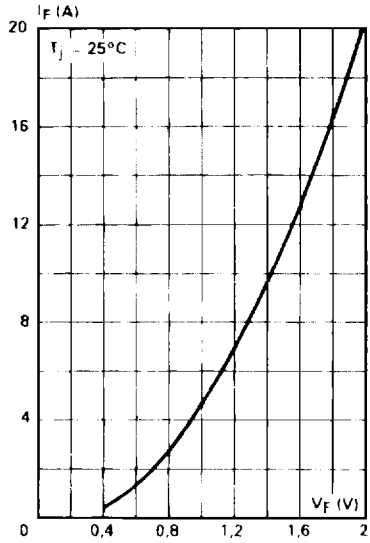


Fig.2 Forward current versus forward voltage at high level (typical values)

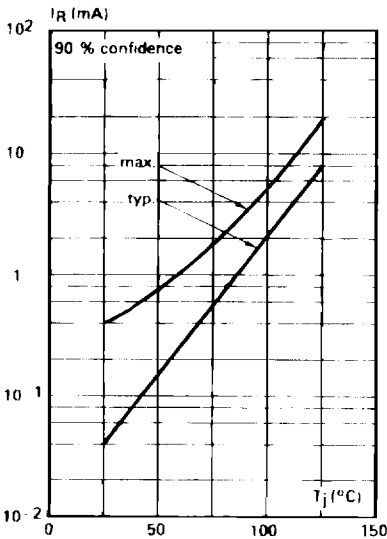


Fig.3 Reverse current versus junction temperature.

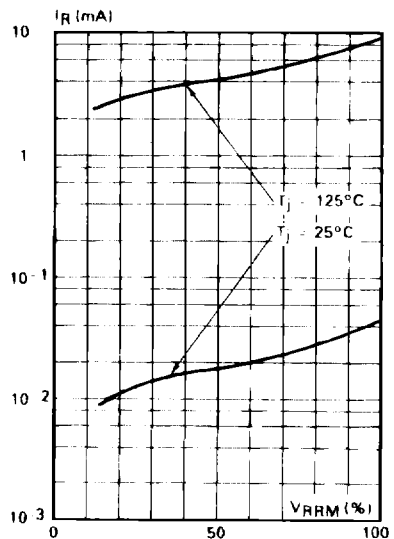


Fig.4 Reverse current versus V_{RRM} in per cent.

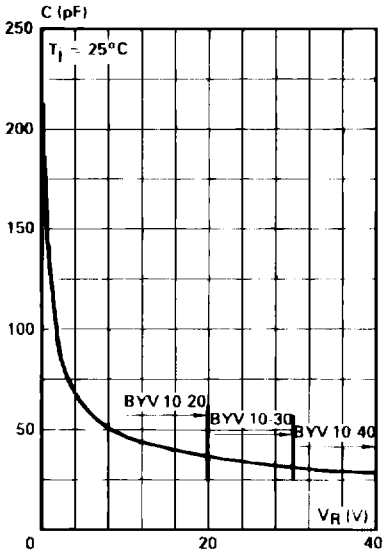


Fig.5 - Capacitance C versus reverse applied voltage V_R (typical values)

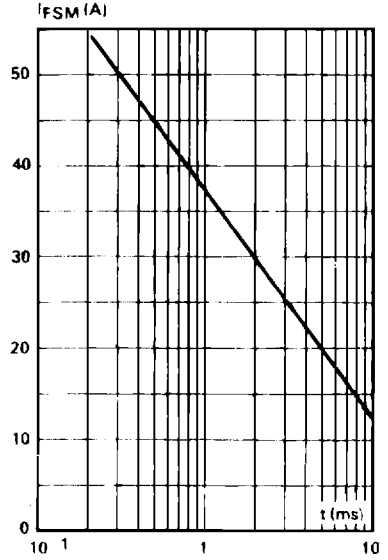


Fig.6 - Surge non-repetitive forward current for a rectangular pulse with $t \leq 10$ ms.

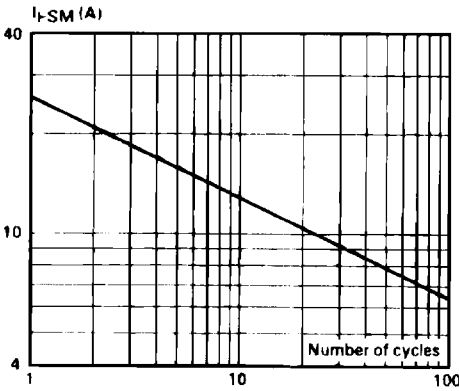


Fig.7 - Surge non-repetitive forward current versus number of cycles.

